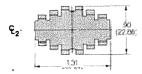
# HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

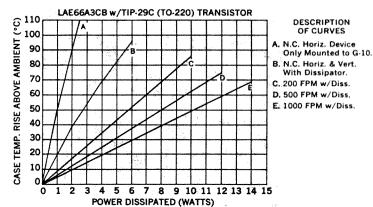
### **LA-A3 Series**







Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
  Derate 0.5 °C/watt for unplated part in natural convection only.
  Derate 3.0 °C/watt for Insulube\* part in natural convection only.

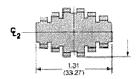
## **Ordering Information**

	IERC PAR	0	Hole patt.	Max.		
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	insulube® 448	Semiconductor Accommodated	ref. no. (see pg. 2-27)	Weight (Grams)
LAOOOA3U LAE66A3U	LA000A3CB LAE66A3CB	LA000A3B LAE66A3B	LACCOA3 LAEGGA3	Undrilled T0-126, T0-220	1	6.1 6.1

Note: See page iv for other finishes.

### **LA-A4 Series**







CASE TEMP. RISE ABOVE AMBIENT (°C) 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 00 DESCRIPTION OF CURVES A. N.C. Horiz, Device Only Mounted to G-10. B. N.C. Horiz. & Vert. With Dissipator. C. 200 FPM w/Diss. D. 500 FPM w/Diss. E. 1000 FPM w/Diss. 3 4 5 6 7 8 9 10 11 12 13 14 15 **POWER DISSIPATED (WATTS)** 

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
  Derate 0.6 °C/watt for unplated part in natural convection only.
  Derate 3.0 °C/watt for Insulube® part in natural convection only.

		Hole patt.	Mar.			
Unplated	Commill Black Anodize	Mil. Black Anodize	insulube* 448	Semiconductor Accommodated	ref. no. (see pg. 2-27)	Weight (Grams)
LA000A4U LAE66A4U	LADDOAGCU LAE66A4CB	LA000A4B LAE66A4B	LADOGA4 LAE6GA4	Undrilled 10-126, 10-220	<u> </u>	7.6 7.6

Note: See page is for other finishes

Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.

# **Mouser Electronics**

**Authorized Distributor** 

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CTS: LAE66A3CB